Product / Package Information

Package	LGA
Body Size (mm)	3 X 5
Ball Count	14
Terminal Finish	Gold

Environmental Information

RoHS Compliant	Yes - with exemption
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.12 E-02	86.20	862000	36.73	367287
Thermosets	Epoxy resin	Proprietary	7.80 E-04	6.00	60000	2.56	25565
Thermosets	Phenol Resin	Proprietary	7.80 E-04	6.00	60000	2.56	25565
Other inorganic materials	Metal Hydroxide	Proprietary	1.95 E-04	1.50	15000	0.64	6391
Other inorganic materials	Carbon Black	1333-86-4	3.90 E-05	0.30	3000	0.13	1278
Subtotal	Subtotal		1.30 E-02	100.0	1000000	42.61	426088

Laminate

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Glass	Continuous filament Fiber Glass	65997-17-3					
Copper & its alloys	Copper	Proprietary					
Thermoset	Bismaleimide/Triazine	13676-54-5					
Thermoset	Epoxy Resin	Proprietary					
Other inorganic materials	Inorganic Filler	Proprietary					
	Laminate Core Subtotal		2.90 E-03	41.40	414285.7143	9.51	95050
Other organic materials	Diethylene Glycol Ethyl Ether Acetate	112-15-2					
Other organic materials	Dipropylene Glycol Methyl Ether	34590-94-8					
Other organic materials	Heavy Aromatic Naphtha (petroleum)	64742-94-5					
	Soldermask Subtotal		1.40 E-03	20.0	200000	4.59	45886
Copper & its alloys	Copper	7440-50-8	1.50 E-03	21.4	214285.7143	4.92	49164
Nickel & its alloys	Nickel	7440-02-0	1.00 E-03	14.3	142857.1429	3.28	32776
Precious metals	Gold	7440-57-5	2.00 E-04	2.86	28571.42857	0.66	6555
Subtotal			7.00 E-03	100.0	1000000	23	229432

Seal Glass

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Glass	Lead borosilicate glass	65997-17-3	7.74 E-04	87.50	875000	2.54	25367
Glass	Aluminosilicate glass	65997-17-3	1.11 E-04	12.50	125000	0.36	3624
Subtotal			8.85 E-04	100	1000000	2.90	28991

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.29 E-03	99	990000	10.79	107911
Precious metals	Palladium	7440-05-3	3.33 E-05	1	10000	0.11	1090
Subtotal			3.33 E-03	100	1000000	10.90	109001

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	4.50 E-03	100	1000000	14.75	147492

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	9.18 E-04	51.00	510000	3.01	30088
Other organic materials	Resin	Proprietary	8.82 E-04	49.00	490000	2.89	28908
Subtotal			1.80 E-03	100.00	1000000	5.90	58997

	Weight (g)	Percentage (%)	PPM
Package Totals	**3.05 E-02**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.

ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary